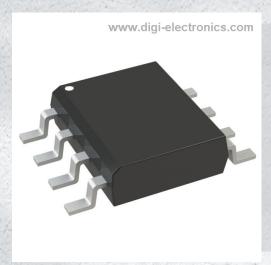


# **DMN4800LSS-13 Datasheet**



https://www.DiGi-Electronics.com

DiGi Electronics Part Number DMN4800LSS-13-DG

Manufacturer Diodes Incorporated

Manufacturer Product Number DMN4800LSS-13

Description MOSFET N-CH 30V 9A 8SOP

Detailed Description N-Channel 30 V 9A (Ta) 1.46W (Ta) Surface Mount 8

-50



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



# **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
DMN4800LSS-13	Diodes Incorporated
Series:	Product Status:
	Active
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
30 V	9A (Ta)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ ld, Vgs:
4.5V, 10V	16m0hm @ 9A, 10V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
1.6V @ 250µA	9.47 nC @ 5 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±25V	798 pF @ 10 V
FET Feature:	Power Dissipation (Max):
	1.46W (Ta)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
8-SO	8-SOIC (0.154", 3.90mm Width)
Base Product Number:	
DMN4800	

# **Environmental & Export classification**

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	





**DMN4800LSS** 

#### **N-CHANNEL ENHANCEMENT MODE MOSFET**

#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C		
30V	14mΩ @ V <sub>GS</sub> = 10V	8.6A		
30 V	20mΩ @ V <sub>GS</sub> = 4.5V	7.1A		

#### Description

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(ON)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

#### **Applications**

- Backlighting
- Power Management Functions
- DC-DC Converters

#### **Features**

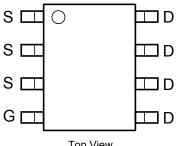
- Low On-Resistance
- Low Input Capacitance
- · Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

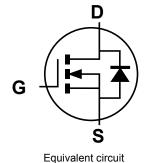
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper lead frame.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.072g (approximate)







Top View Internal Schematic



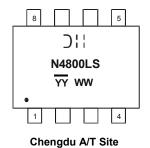
#### **Ordering Information** (Note 4)

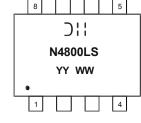
Part Number	Case	Packaging
DMN4800LSS-13	SO-8	2500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

#### **Marking Information**





Shanghai A/T Site

⊃¦¦ = Manufacturer's Marking
 N4800LS = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Year (ex: 13 = 2013)
 WW = Week (01 - 53)

YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)





### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			$V_{GSS}$	±25	V
Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$		I <sub>D</sub>	8.6 6.3	Α	
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	11.8 9.0	А
Maximum Body Diode Forward Current (Note 6)			I <sub>S</sub>	2.4	Α
Pulsed Drain Current (Note 7)			I <sub>DM</sub>	50	Α

#### **Thermal Characteristics**

Characteristic		Symbol	Value	Units	
Total Dower Dissipation (Note 5)	$T_A = +25$ °C	D	1.46	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	P <sub>D</sub>	0.9	VV	
Thermal Resistance, Junction to Ambient (Note 5)	harmal Desistance, Junetian to Ambient (Note 5) Steady state		86	°C/W	
Thermal Resistance, Junction to Ambient (Note 3)	t<10s	$R_{\theta JA}$	46	C/VV	
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	D-	1.7	W	
Total Fower Dissipation (Note 0)	$T_A = +70^{\circ}C$	P <sub>D</sub>	1.0		
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	D :	75		
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	40	°C/W	
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	15		
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C	

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)	-					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30		_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_		1	μΑ	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_		±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.8	1.2	1.6	٧	$V_{DS} = V_{GS}$ , $I_{D} = 250 \mu A$
Static Drain-Source On-Resistance	D		11	14	mΩ	$V_{GS} = 10V, I_D = 9A$
Static Dialit-Source Off-Resistance	R <sub>DS (ON)</sub>		14	20	11122	$V_{GS} = 4.5V, I_D = 7A$
Forward Transconductance	9fs	_	8		S	$V_{DS} = 10V, I_D = 9A$
Diode Forward Voltage (Note 8)	$V_{SD}$		0.72	0.94	V	$V_{GS} = 0V, I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C <sub>iss</sub>	_	798		pF	
Output Capacitance	Coss		128		pF	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V -f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	122	_	pF	1 - 1.0MH2
Gate Resistance	$R_G$	_	1.37	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge	Qg	_	8.7	_		
Gate-Source Charge	Q <sub>gs</sub>	_	1.7	_	nC	$V_{GS} = 5V, V_{DS} = 15V, I_D = 9A$
Gate-Drain Charge	Q <sub>qd</sub>	_	2.4	_		
Turn-On Delay Time	t <sub>d(on)</sub>	_	5.03	_		
Rise Time	t <sub>r</sub>	_	4.50	_		$V_{DD}$ = 15V, $V_{GEN}$ = 10V, $R_{L}$ = 15 $\Omega$ , $R_{G}$ = 6.0 $\Omega$ , $I_{D}$ = 1A
Turn-Off Delay Time	t <sub>d(off)</sub>	_	26.33	_	ns	
Fall Time	t <sub>f</sub>	_	8.55	_		

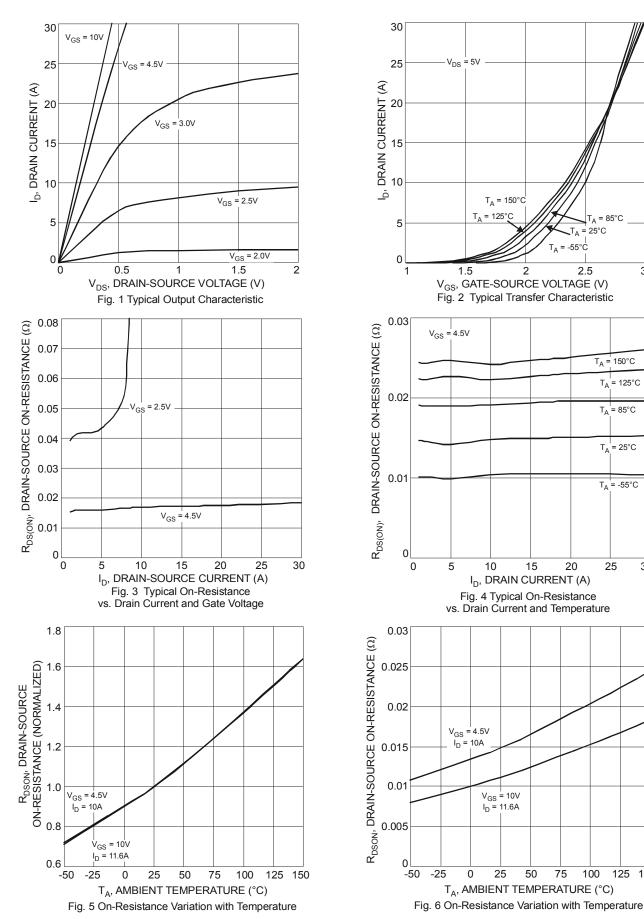
Notes:

- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
   Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout
   Repetitive rating, pulse width limited by junction temperature.
   Short duration pulse test used to minimize self-heating effect.
   Guaranteed by design. Not subject to product testing.

3

30







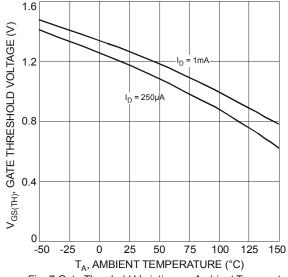
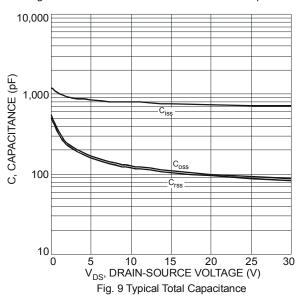


Fig. 7 Gate Threshold Variation vs. Ambient Temperature



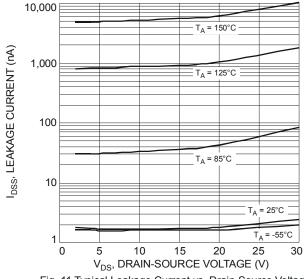
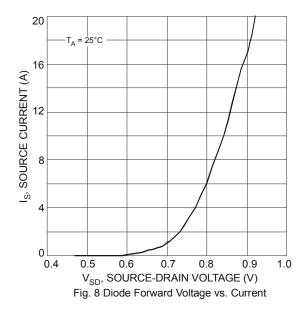
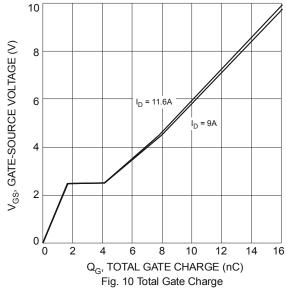
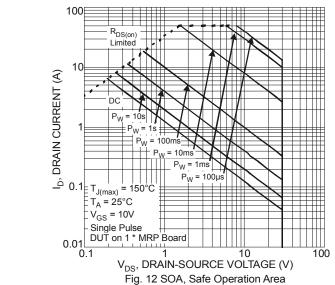


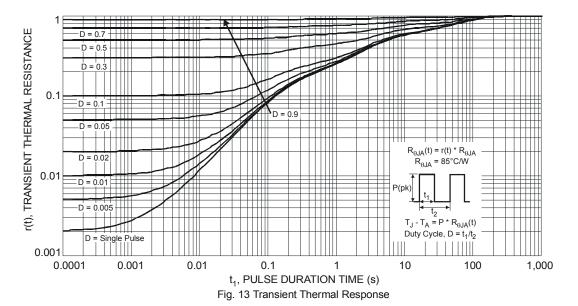
Fig. 11 Typical Leakage Current vs. Drain-Source Voltage



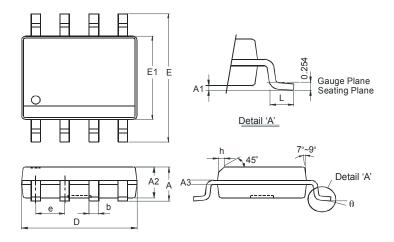






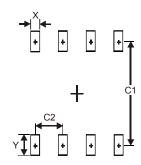


## **Package Outline Dimensions**

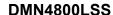


SO-8					
Dim	Min	Max			
Α	-	1.75			
A1	0.10	0.20			
A2	1.30	1.50			
А3	0.15	0.25			
b	0.3	0.5			
D	4.85	4.95			
Е	5.90	6.10			
E1	3.85	3.95			
е	<b>e</b> 1.27 Typ				
h	-	0.35			
L	0.62	0.82			
θ	0°	8°			
All Dimensions in mm					

## Suggested Pad Layout



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27





#### IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2012, Diodes Incorporated

www.diodes.com



## **OUR CERTIFICATE**

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we striciy control the quality of products and services. Welcome your RFQ to Email: Info@DiGi-Electronics.com

















Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com